

ABSTRACT <sup>1</sup> OF THE INVENTION

A printed circuit board 1 providing superior adhesion between a substrate 2 and a conductor pattern 3 and preventing damage of the substrate 2. The width c of the bottom surface 310 of the conductor pattern 3 is greater than the width d of the top surface 320. Accordingly, the conductor pattern 3 has a trapezoidal cross-section. The two side surfaces 315 of a lower portion 31 of the conductor pattern 3 are coated by a solder resist. The two side surfaces 325 at the upper portion 32 of the conductor pattern 3 are exposed from the solder resist 4. A solder ball 6 engages the two side surfaces 325.